

2SB0789G

Silicon PNP epitaxial planar type

For low-frequency driver amplification

■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- Large collector power dissipation P_C

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-120	V
Collector-emitter voltage (Base open)	V_{CEO}	-120	V
Emitter-base voltage (Collector open)	V_{EBO}	-5	V
Collector current	I_C	-0.5	A
Peak collector current	I_{CP}	-1	A
Collector power dissipation *	P_C	1	W
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: Print circuit board: Copper foil area of 1 cm^2 or more, and the board thickness of 1.7 mm for the collector portion.

■ Package

- Code
MiniP3-F2
- Pin Name
1: Base
2: Collector
3: Emitter

■ Marking Symbol: E

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

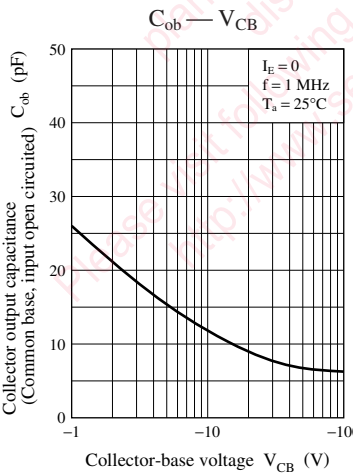
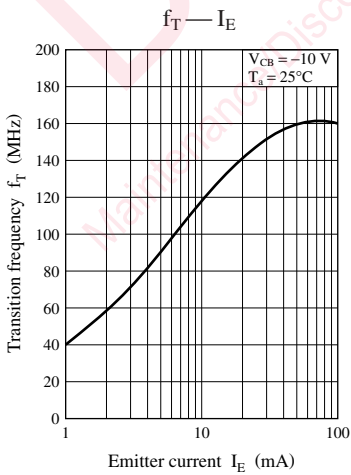
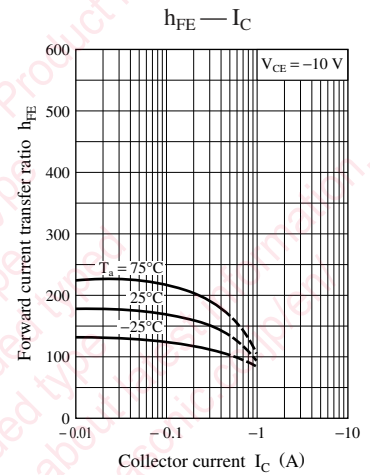
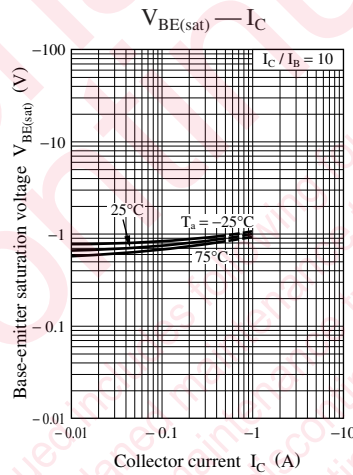
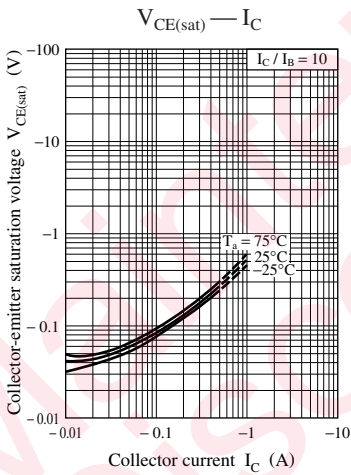
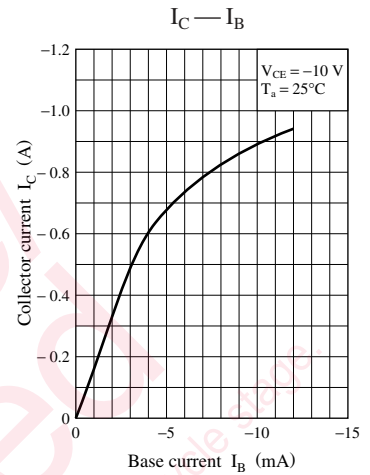
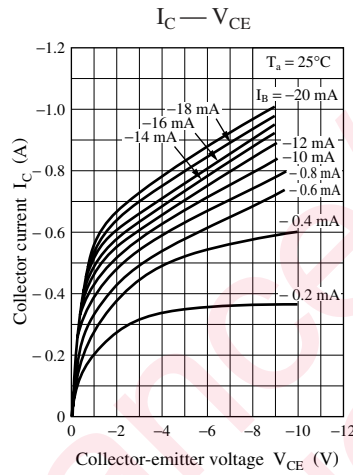
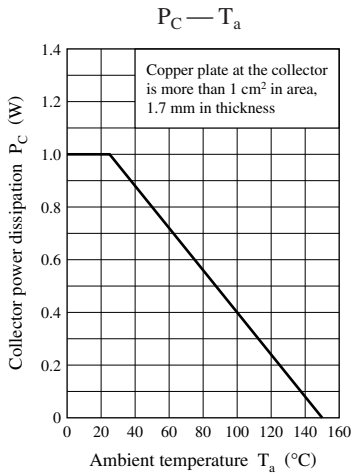
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -100\ \mu\text{A}$, $I_B = 0$	-120			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10\ \mu\text{A}$, $I_C = 0$	-5			V
Forward current transfer ratio *1	h_{FE1} *2	$V_{CE} = -10\ \text{V}$, $I_C = -150\ \text{mA}$	90		220	—
	h_{FE2}	$V_{CE} = -5\ \text{V}$, $I_C = -500\ \text{mA}$	50			
Collector-emitter saturation voltage *1	$V_{CE(sat)}$	$I_C = -500\ \text{mA}$, $I_B = -50\ \text{mA}$		-0.2	-0.6	V
Base-emitter saturation voltage *1	$V_{BE(sat)}$	$I_C = -500\ \text{mA}$, $I_B = -50\ \text{mA}$		-0.85	-1.20	V
Transition frequency	f_T	$V_{CB} = -10\ \text{V}$, $I_E = 50\ \text{mA}$, $f = 200\ \text{MHz}$		120		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10\ \text{V}$, $I_E = 0$, $f = 1\ \text{MHz}$			30	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement

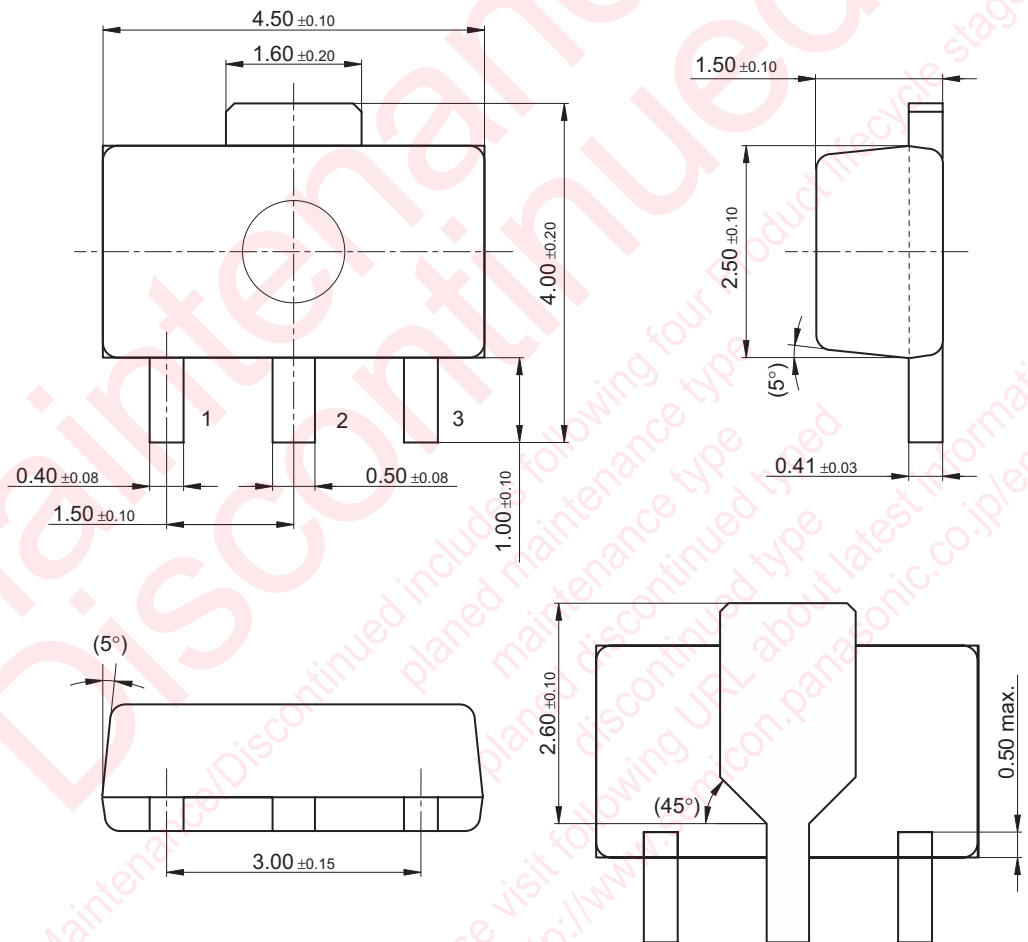
*2: Rank classification

Rank	Q	R
h_{FE1}	90 to 155	130 to 220



MiniP3-F2

Unit: mm



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